L Number	Hits		DB	Time stamp
1	292878		USPAT;	2004/11/07 20:27
		collaborat\$3	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
2	254032		USPAT;	2004/11/07 20:29
		(control permi\$5 security)) authenticat\$3	US-PGPUB;	
i			EPO; JPO;	
			DERWENT; IBM TDB	
3	2868995	conferee participant member	USPAT;	2004/11/07 20:30
]			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
4	9975	(login log-in password (access\$3 near3	IBM_TDB USPAT;	2004/11/07 20:31
-	33.3	(control permi\$5 security)) authenticat\$3)	US-PGPUB;	2004/11/07 20:51
		with (conferee participant member)	EPO; JPO;	
'			DERWENT;	
5	39218	(material document project) with	IBM_TDB USPAT;	2004/11/07 20:32
	39210	((conferenc\$3 teleconferenc\$3 meeting	US-PGPUB;	2004/11/0/ 20:32
		collaborat\$3) discussion)	EPO; JPO;	
		·	DERWENT;	
_	. 105156	/	IBM_TDB	
6	125156	(material document project) same (design\$3 manufacturing fabricat\$3 product performance	USPAT; US-PGPUB;	2004/11/07 21:37
		evaluation) same (semiconductor chip ic	EPO; JPO;	
ĺ		(integrated adj1 circuit))	DERWENT;	
_	_		IBM_TDB	
7	7	1 (USPAT;	2004/11/07 20:35
		collaborat\$3) and ((login log-in password (access\$3 near3 (control permi\$5 security))	US-PGPUB; EPO; JPO;	
		authenticat\$3) with (conferee participant	DERWENT;	
		member)) and ((material document project)	IBM_TDB	
1		with ((conferenc\$3 teleconferenc\$3 meeting	}	
		collaborat\$3) discussion)) and ((material document project) same (design\$3		
		manufacturing fabricat\$3 product performance	Ì	
		evaluation) same (semiconductor chip ic		
	1554060	(integrated adj1 circuit)))		
8	1554962	(material document project) same (design\$3 manufacturing fabricat\$3 product performance	USPAT;	2004/11/07 20:40
		evaluation)	US-PGPUB; EPO; JPO;	
			DERWENT;	
		(IBM_TDB	
9	1313	(conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password	USPAT; US-PGPUB;	2004/11/07 20:41
		(access\$3 near3 (control permi\$5 security))	EPO; JPO;	
		authenticat\$3) and (conferee participant	DERWENT;	
		member) and ((material document project)	IBM_TDB	
		with ((conferenc\$3 teleconferenc\$3 meeting		
		collaborat\$3) discussion)) and ((material document project) same (design\$3		
		manufacturing fabricat\$3 product performance		
		evaluation))		
10	766007	(design\$3 manufacturing fabricat\$3 product	USPAT;	2004/11/07 21:09
		performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))	US-PGPUB;	
		direct chip is (integrated adji circuit))	EPO; JPO; DERWENT;	
<u>.</u>			IBM_TDB	
				·

11	438			10001/00/00 00 10
11	431	((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:43
12	. •	(((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:45
13	52	((((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale) and chat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:45
14	52	-	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:39
15	52	(((((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale) and (chat chatroom) and (link\$3 hyperlink\$3) 20040205644.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:05
		EUUTUEUJUTT.URFM.	USPAI	2004/11/07 21:05

17	36	(("20020156929") or ("20040205644") or	USPAT;	2004/11/07 21:09
		("20040107256") or ("20040107249") or	US-PGPUB;	
		("20040107125") or ("20040103040") or	EPO; JPO;	
		("20030192029") or ("20030154387") or	DERWENT;	
		("20030152904") or ("20030126033") or	IBM_TDB	
		("20030120557") or ("20030023686") or		
		("20020184191") or ("20010042030") or		
		("6615166") or ("6611822") or ("6581039") or		
	1	("6571235") or ("5867494")).PN.		
18	21	((("20020156929") or ("20040205644") or	USPAT;	2004/11/07 21:09
	i	("20040107256") or ("20040107249") or	US-PGPUB;	·
		("20040107125") or ("20040103040") or	EPO; JPO;	
		("20030192029") or ("20030154387") or	DERWENT;	
		("20030152904") or ("20030126033") or	IBM TDB	
		("20030120557") or ("20030023686") or	_	
		("20020184191") or ("20010042030") or		
		("6615166") or ("6611822") or ("6581039") or		
	1	("6571235") or ("5867494")).PN.) and		
	1	((design\$3 manufacturing fabricat\$3 product		
İ	1	performance evaluation) with (semiconductor		
	1	circuit chip ic (integrated adjl circuit)))		
19	3577	(conferenc\$3 teleconferenc\$3 meeting	USPAT;	2004/11/07 21:38
		collaborat\$3) same ((design\$3 manufacturing	US-PGPUB;	2004/11/07 21:30
		fabricat\$3 product performance evaluation)	EPO; JPO;	
		with (semiconductor chip ic (integrated adj1	DERWENT;	
		circuit)))	IBM TDB	
20	3560	(conferenc\$3 teleconferenc\$3 meeting	USPAT;	2004/11/07 21:38
		collaborat\$3) with ((design\$3 manufacturing	US-PGPUB;	2004/11/07 21:38
		fabricat\$3 product performance evaluation)	EPO; JPO;	
		with (semiconductor circuit chip ic	DERWENT;	
		(integrated adj1 circuit)))	IBM TDB	
21	4959	, , , ,	USPAT:	2004/11/05 01 20
21	4939	collaborat\$3) same ((design\$3 manufacturing	,	2004/11/07 21:39
	}	fabricat\$3 product performance evaluation)	US-PGPUB;	
		with (semiconductor chip ic (integrated adjl	EPO; JPO;	
		circuit)))) ((conferenc\$3 teleconferenc\$3	DERWENT;	
		meeting collaborat\$3) with ((design\$3	IBM_TDB	
		manufacturing fabricat\$3 product performance		
		evaluation) with (semiconductor circuit chip		
ļ	,			
22	14	ic (integrated adj1 circuit)))) .		0004/05/05 05 55
~~	14	(((conferenc\$3 teleconferenc\$3 meeting	USPAT;	2004/11/07 21:39
		collaborat\$3) same ((design\$3 manufacturing	US-PGPUB;	
		fabricat\$3 product performance evaluation)	EPO; JPO;	
		with (semiconductor chip ic (integrated adj1	DERWENT;	
		circuit)))) ((conferenc\$3 teleconferenc\$3	IBM_TDB	
		meeting collaborat\$3) with ((design\$3		
1		manufacturing fabricat\$3 product performance		
		evaluation) with (semiconductor circuit chip		
		ic (integrated adj1 circuit))))) and (chat		
	<u></u>	chatroom)		